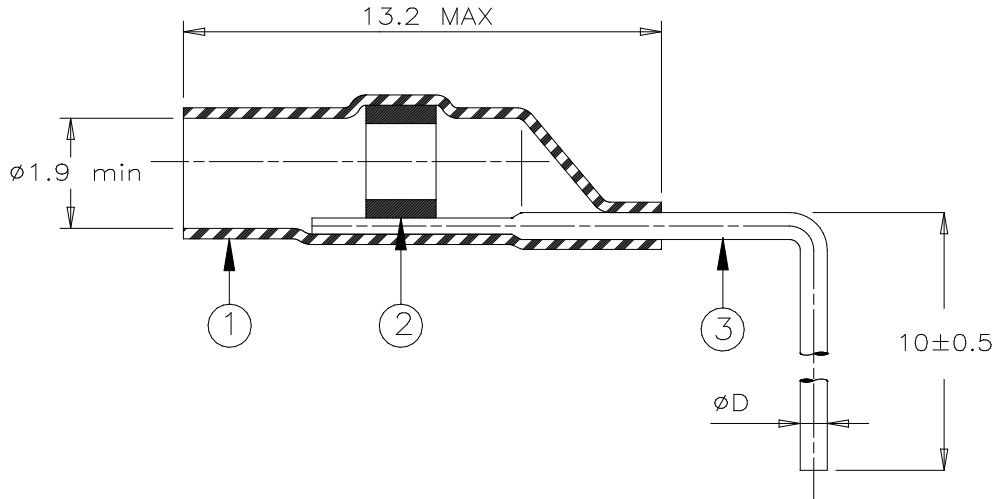


# CUSTOMER DRAWING



Product Name	$\phi D$	$\phi X$
B-801-06	0.68	0.8
B-801-08	0.88	1

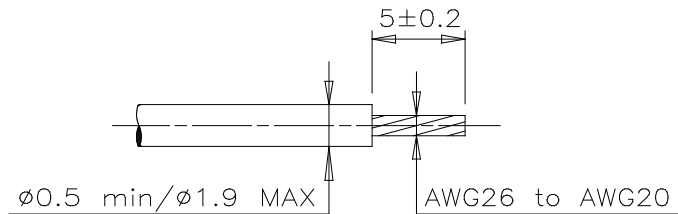
## MATERIALS


- INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
- SOLDER PREFORM WITH FLUX:  
SOLDER: TYPE Sn62 Pb36 Ag2 per ANSI-J-STD-006.  
FLUX: TYPE ROL0 per ANSI-J-STD-004.
- PIN: Phosphor bronze coated with Sn60 Pb40 solder alloy.

## APPLICATION

- These controlled soldering devices are designed for termination of a tin or silver plated stranded AWG26, AWG24 and AWG22 conductor having an insulation rated for at least +125°C on a PC board with  $\phi X$  diameter hole. If AWG20 wire is used, pre-tinning is recommended.
- Temperature range: -55°C to +150°C. For application tooling, contact your local TE Connectivity technical service.

For best results, prepare the wire as shown:



		<b>Raychem</b> THERMOFIT DEVICES		TITLE: <b>PINPAK* DEVICE FOR PCB TERMINATION</b>		
				DOCUMENT NO.: <b>B-801-0X</b>		
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]						
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A		ANGLES: N/A ROUGHNESS IN MICRON		TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		
DRAWN BY: M. FORONDA		DATE: 22-Mar-1999				
SCALE: NTS			SIZE: A	SHEET: 1 of 1		

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